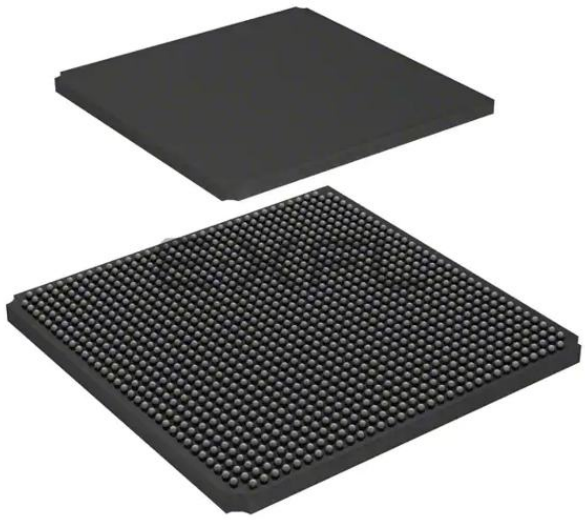
Lattice Semiconductor Corporation - LFE2M70SE-6FN1152I Datasheet



Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Not For New Designs
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	436
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-6fn1152i

LatticeECP2/M Family Data Sheet Architecture

September 2013 **Data Sheet DS1006**

Architecture Overview

Each LatticeECP2/M device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sysDSP™ Digital Signal Processing blocks, as shown in Figure 2-1. In addition, the LatticeECP2M family contains SERDES Quads in one or more of the corners. Figure 2-2 shows the block diagram of ECP2M20 with one quad.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional Unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The LatticeECP2/M devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large dedicated 18K fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths of RAM or ROM. In addition, LatticeECP2/M devices contain up to two rows of DSP Blocks. Each DSP block has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The LatticeECP2M devices feature up to 16 embedded 3.125Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of four SERDES channels along with its Physical Coding Sub-layer (PCS) block, creates a quad. The functionality of the SERDES/PCS Quads can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every quad can be programmed by a soft IP interface, referred to as the SERDES Client Interface (SCI). These quads (up to four) are located at the corners of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the LatticeECP2/M devices are arranged in eight banks, allowing the implementation of a wide variety of I/O standards. In addition, a separate I/O bank is provided for the programming interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. The PIC logic also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as SPI4.2, along with memory interfaces including DDR2.

The LatticeECP2/M registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The LatticeECP2/M architecture provides two General PLLs (GPLL) and up to six Standard PLLs (SPLL) per device. In addition, each LatticeECP2/M family member provides two DLLs per device. The GPLLs and DLLs blocks are located in pairs at the end of the bottom-most EBR row; the DLL block is located towards the edge of the device. The SPLL blocks are located at the end of the other EBR/DSP rows.

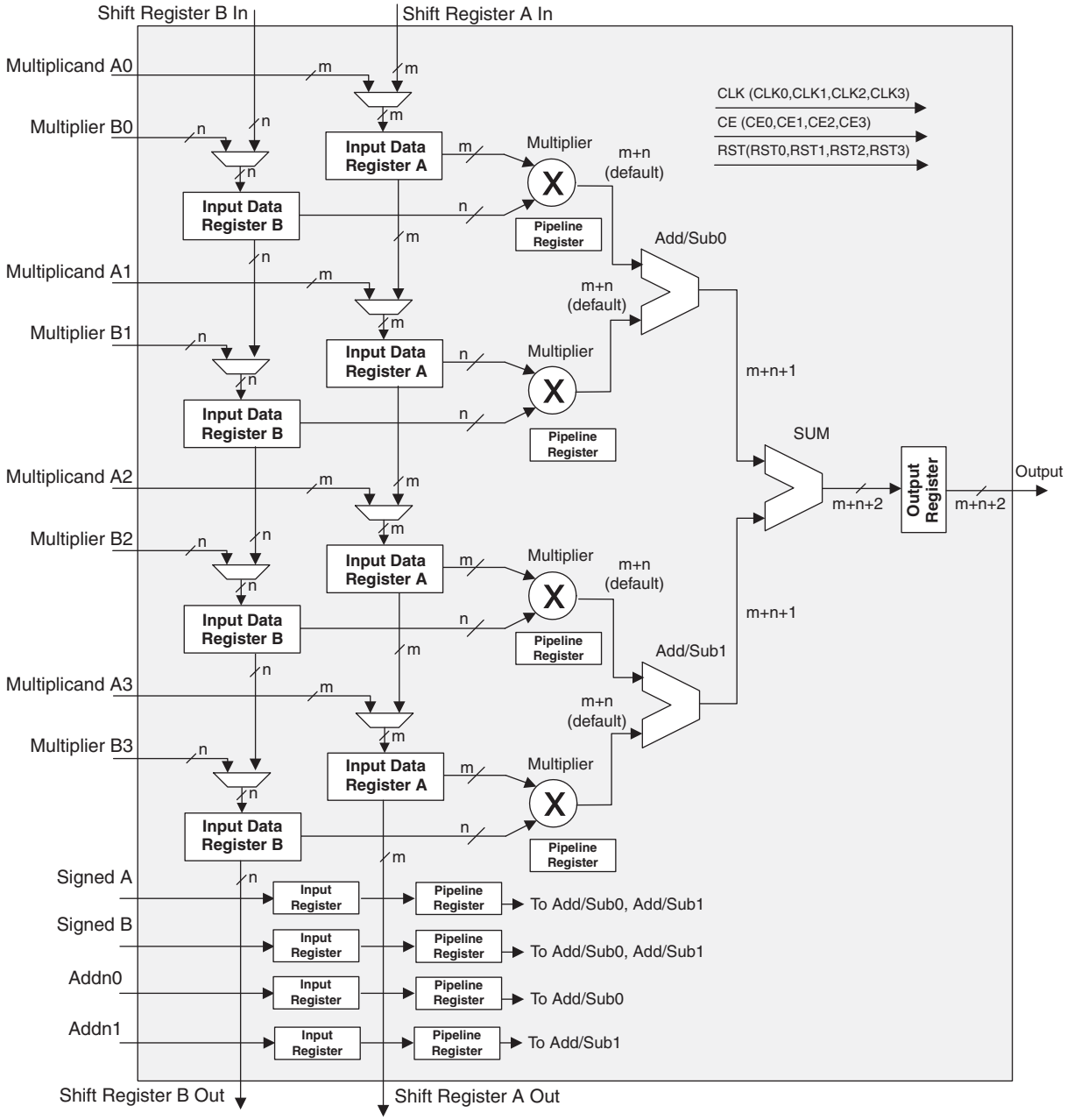
The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual boot support is located toward the center of this EBR row. The Ball Grid Array (BGA) package devices in the LatticeECP2/M family supports a sysCONFIG™ port located in the corner between banks four and five, which allows for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator. The LatticeECP2/M devices use 1.2V as their core voltage.

MULTADDSUBSUM sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. Additionally the operands A2 and B2 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A3 and B3. The result of both addition/subtraction are added in a summation block. The user can enable the input, output and pipeline registers. Figure 2-26 shows the MULTADDSUBSUM sysDSP element.

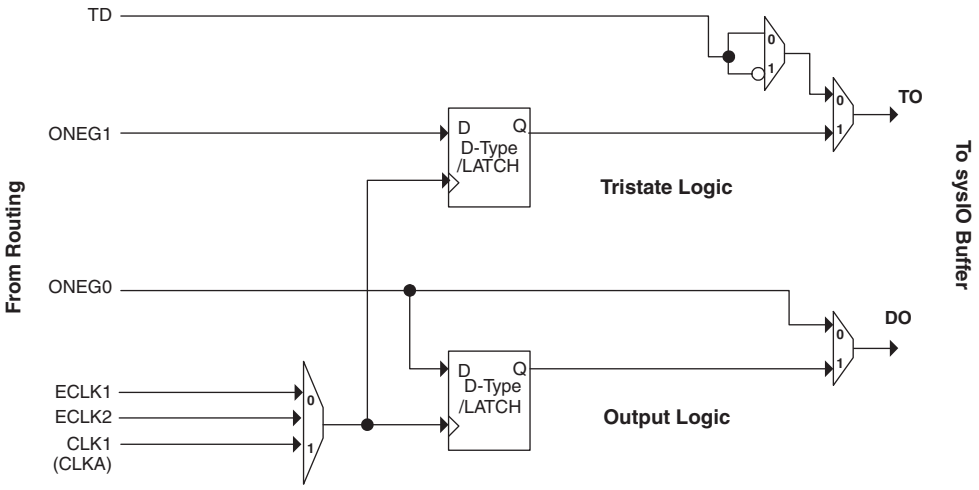
Figure 2-26. MULTADDSUBSUM



Clock, Clock Enable and Reset Resources

Global Clock, Clock Enable and Reset signals from routing are available to every DSP block. Four Clock, Reset and Clock Enable signals are selected for the sysDSP block. From four clock sources (CLK0, CLK1, CLK2, CLK3)

Figure 2-32. Output and Tristate Block, Top Edge



Note: Simplified version does not show CE and SET/RESET details.

Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysI/O buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-31 shows the diagram of the Tristate Register Block with the Output Block for the left, right and bottom edges and Figure 2-32 shows the diagram of the Tristate Register Block with the Output Block for the top edge.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 and OPOS1 are fed into registers on the positive edge of the clock. Then in the next clock the registered OPOS1 is latched. A multiplexer running off the same clock cycle selects the correct register for feeding to the output (D0).

Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing, one of the edge clocks (ECLK1/ ECLK2) and a DQS signal provided from the programmable DQS pin and provided to the input register block. The clock can optionally be inverted.

DDR Memory Support

Certain PICs have additional circuitry to allow the implementation of high speed source synchronous and DDR memory interfaces. The support varies by the edge of the device as detailed below.

Left and Right Edges

PICs on these edges have registered elements that support DDR memory interfaces. One of every 16 PIOs contains a delay element to facilitate the generation of DQS signals. The DQS signal feeds the DQS bus that spans the set of 16 PIOs. Figure 2-33 shows the assignment of DQS pins in each set of 16 PIOs.

Bottom Edge

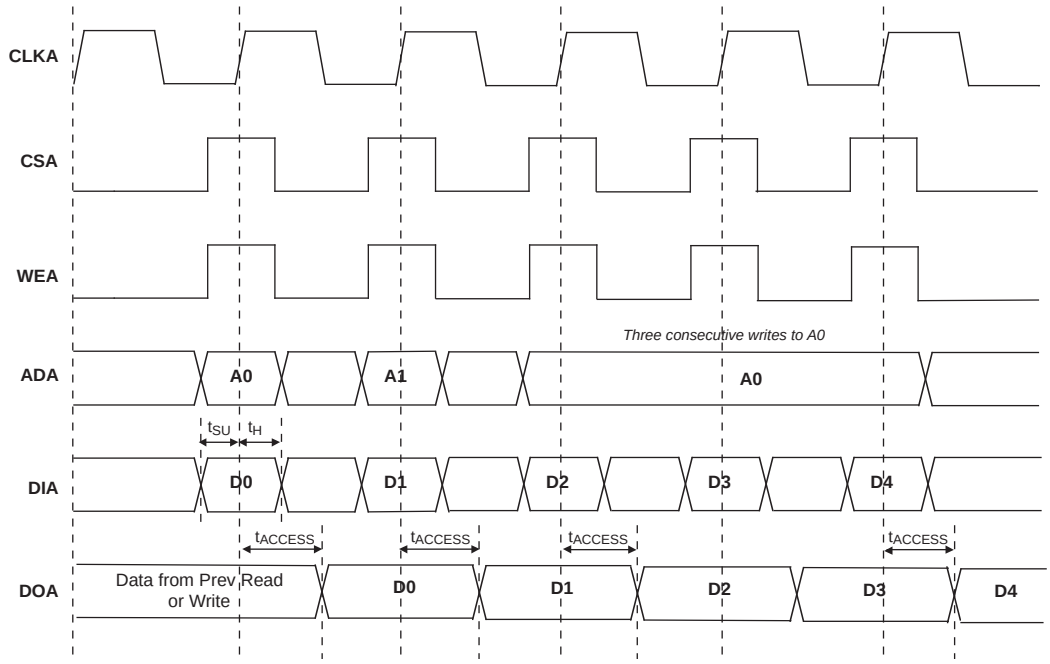
PICs on the bottom edge have registered elements that support DDR memory interfaces. One of every 18 PIOs contains a delay element to facilitate the generation of DQS signals. The DQS signal feeds the DQS bus that spans the set of 18 PIOs. Figure 2-34 shows the assignment of DQS pins in each set of 18 PIOs.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{SUE}	Clock to Data Setup - PIO Input Register	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
t_{HE}	Clock to Data Hold - PIO Input Register	LFE2-6	0.90	—	1.10	—	1.30	—	ns
		LFE2-12	0.90	—	1.10	—	1.30	—	ns
		LFE2-20	0.90	—	1.10	—	1.30	—	ns
		LFE2-35	0.90	—	1.10	—	1.30	—	ns
		LFE2-50	0.90	—	1.10	—	1.30	—	ns
		LFE2-70	0.90	—	1.10	—	1.30	—	ns
		LFE2M20	0.90	—	1.10	—	1.30	—	ns
		LFE2M35	0.90	—	1.10	—	1.30	—	ns
		LFE2M50	1.20	—	1.40	—	1.60	—	ns
		LFE2M70	1.20	—	1.40	—	1.60	—	ns
		LFE2M100	1.20	—	1.40	—	1.60	—	ns
t_{SU_DELE}	Clock to Data Setup - PIO Input Register with Data Input Delay	LFE2-6	1.00	—	1.30	—	1.60	—	ns
		LFE2-12	1.00	—	1.30	—	1.60	—	ns
		LFE2-20	1.00	—	1.30	—	1.60	—	ns
		LFE2-35	1.00	—	1.30	—	1.60	—	ns
		LFE2-50	1.00	—	1.30	—	1.60	—	ns
		LFE2-70	1.00	—	1.30	—	1.60	—	ns
		LFE2M20	1.20	—	1.60	—	1.90	—	ns
		LFE2M35	1.20	—	1.60	—	1.90	—	ns
		LFE2M50	1.20	—	1.60	—	1.90	—	ns
		LFE2M70	1.20	—	1.60	—	1.90	—	ns
		LFE2M100	1.20	—	1.60	—	1.90	—	ns

Figure 3-11. Write Through (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

sysCLOCK SPLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)	Without external capacitor	33	—	420	MHz
		With external capacitor[5, 6]	2	—	420	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)	Without external capacitor	33	—	420	MHz
		With external capacitor[5]	5	—	50	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)	Without external capacitor	0.258	—	210	MHz
		With external capacitor[5]	0.039	—	25	MHz
f_{VCO}	PLL VCO Frequency		640	—	1280	MHz
f_{PFD}	Phase Detector Input Frequency	Without external capacitor	33	—	420	MHz
		With external capacitor[6]	2	—	50	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default Duty Cycle Selected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	±0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	$f_{OUT} \geq 100$ MHz	—	—	±125	ps
		$50 \leq f_{OUT} < 100$ MHz	—	—	0.025	UIPP
		$f_{OUT} < 50$ MHz	—	—	0.04	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider Ratio = Integer	—	—	±250	ps
t_W	Output Clock Pulse Width	At 90% or 10%	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time	Without external capacitor	—	—	150	µs
		With external capacitor[5]	—	—	500	µs
t_{IPJIT}	Input Clock Period Jitter		—	—	±200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width (RSTK)		15	—	—	ns
	Reset Signal Pulse Width (RST)	Without external capacitor	500	—	—	ns
		With external capacitor[5]	20	—	—	µs

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock and no additional I/O pins toggling.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. Phase accuracy of CLKOS compared to CLKOP.
5. Value of external capacitor: 5.6 nF ±20%, NPO dielectric, ceramic chip capacitor, 1206 or smaller package, connected to PLLCAP pin.
6. f_{OUT} (max) = f_{IN} * 10 for f_{IN} < 5MHz.

LatticeECP2M Power Supply and NC

Signal	256 fpBGA	484 fpBGA
V_{CC}	G7, G9, H7, J10, K10, K8	J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13
V_{CCIO0}	E7	B5, B9, E7, H9
V_{CCIO1}	E10	D13, E16, H14
V_{CCIO2}	E14, G12	E21, G18, J15, K19
V_{CCIO3}	K12, M14	N19, P15, T18, V21
V_{CCIO4}	M10, P12	AA18, R14, V16, W13
V_{CCIO5}	M7, P5	AA5, R9, V7, W10
V_{CCIO6}	K5, M3	N4, P8, T5, V2
V_{CCIO7}	E3, G5	E2, G5, J8, K4
V_{CCIO8}	T15	AA22, U19
V_{CCJ}	K7	W4
V_{CCAUX}	G8, H10, J7, K9	H11, H12, L15, L8, M15, M8, R11, R12
V_{CCPLL}	G10	R8, H15, H8, R15
SERDES Power[3]	C15, B15, C12, A12, C11, C10, C14, C13, B9, C9, C5, C4, C8, C7, A6, C6, B3, C3	C22, B22, C19, A19, C18, C17, C21, C20, B16, C16, C12, C11, C15, C14, A13, C13, B10, C10
GND[1]	A1, A15, A16, A3, A9, B12, B6, E15, E2, H14, H8, H9, J3, J8, J9, M15, M2, P9, R12, R5, T1, T16	A1, A10, A16, A22, AA19, AA4, AB1, AB22, B13, B19, B4, D16, D2, D21, D7, G19, G4, H10, H13, J14, J9, K10, K11, K12, K13, K15, K20, K3, K8, L10, L11, L12, L13, M10, M11, M12, M13, N10, N11, N12, N13, N15, N20, N3, N8, P14, P9, R10, R13, T19, T4, W16, W2, W21, W7, Y10, Y13
NC[2]	D10, D11, D12, D13, D14, D4, D5, D6, D7, E11, E6, E8, E9, F10, F7, F8, F9	**LFE2M20:** D14, D15, E14, E15, F13, F14, F15, G12, G13, G14, G15 **LFE2M35:** D14, D15, E14, E15, F13, F14, F15, G12, G13, G14, G15, U6 **LFE2M50:** Y15, W15, AB20, AB21, AA20, AB19, AB18, Y22, Y21, Y17, Y18, Y16, W17, Y19, Y20, W19, W18, V17, V18, D15, G14, G15, D14, E15, E14, F15, F14, F13, G12, G13

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. For package migration across device densities, the designer must comprehend the package pin requirements for the SERDES blocks. Specifically, the SERDES power pins of the largest density device must be accounted to accommodate migration to other smaller devices using the same package. Please refer to TN1160, LatticeECP2/M Density Migration for more details.

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D2	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
D1	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
GND	GNDIO7	-			GNDIO7	-		
F6	PL5A	7	LDQ8	T	PL18A	7	LDQ21	T
F5	PL5B	7	LDQ8	C	PL18B	7	LDQ21	C
VCCIO	VCCIO7	7			VCCIO7	7		
E4	PL6A	7	LDQ8	T (LVDS)*	PL19A	7	LDQ21	T (LVDS)*
E3	PL6B	7	LDQ8	C (LVDS)*	PL19B	7	LDQ21	C (LVDS)*
E2	PL7A	7	LDQ8	T	PL20A	7	LDQ21	T
E1	PL7B	7	LDQ8	C	PL20B	7	LDQ21	C
GND	GNDIO7	-			GNDIO7	-		
H6	PL8A	7	LDQS8	T (LVDS)*	PL21A	7	LDQS21	T (LVDS)*
H5	PL8B	7	LDQ8	C (LVDS)*	PL21B	7	LDQ21	C (LVDS)*
F2	PL9A	7	LDQ8	T	PL22A	7	LDQ21	T
VCCIO	VCCIO7	7			VCCIO7	7		
F1	PL9B	7	LDQ8	C	PL22B	7	LDQ21	C
H8	PL10A	7	LDQ8	T (LVDS)*	PL23A	7	LDQ21	T (LVDS)*
J9	PL10B	7	LDQ8	C (LVDS)*	PL23B	7	LDQ21	C (LVDS)*
G4	PL11A	7	LDQ8	T	PL24A	7	LDQ21	T
GND	GNDIO7	-			GNDIO7	-		
G3	PL11B	7	LDQ8	C	PL24B	7	LDQ21	C
H7	PL12A	7	LDQ16	T (LVDS)*	PL25A	7	LDQ29	T (LVDS)*
J8	PL12B	7	LDQ16	C (LVDS)*	PL25B	7	LDQ29	C (LVDS)*
G2	PL13A	7	LDQ16	T	PL26A	7	LDQ29	T
G1	PL13B	7	LDQ16	C	PL26B	7	LDQ29	C
H3	PL14A	7	LDQ16	T (LVDS)*	PL27A	7	LDQ29	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO7	7		
H4	PL14B	7	LDQ16	C (LVDS)*	PL27B	7	LDQ29	C (LVDS)*
J5	PL15A	7	LDQ16	T	PL28A	7	LDQ29	T
J4	PL15B	7	LDQ16	C	PL28B	7	LDQ29	C
J3	PL16A	7	LDQS16	T (LVDS)*	PL29A	7	LDQS29	T (LVDS)*
GND	GNDIO7	-			GNDIO7	-		
K4	PL16B	7	LDQ16	C (LVDS)*	PL29B	7	LDQ29	C (LVDS)*
H1	PL17A	7	LDQ16	T	PL30A	7	LDQ29	T
H2	PL17B	7	LDQ16	C	PL30B	7	LDQ29	C
VCCIO	VCCIO7	7			VCCIO7	7		
K6	PL18A	7	LDQ16	T (LVDS)*	PL31A	7	LDQ29	T (LVDS)*
K7	PL18B	7	LDQ16	C (LVDS)*	PL31B	7	LDQ29	C (LVDS)*
J1	PL19A	7	LDQ16	T	PL32A	7	LDQ29	T
J2	PL19B	7	LDQ16	C	PL32B	7	LDQ29	C
GND	GNDIO7	-			GNDIO7	-		
VCCIO	VCCIO7	7			VCCIO7	7		
K3	PL23A	7	LDQ24	T	PL36A	7	LDQ37	T
K2	PL23B	7	LDQ24	C	PL36B	7	LDQ37	C
GND	GNDIO7	-			GNDIO7	-		
K1	PL24A	7	LDQS24***	T (LVDS)*	PL37A	7	LDQS37***	T (LVDS)*

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ6	PB16A	5	BDQ15	T
AK6	PB16B	5	BDQ15	C
VCCIO	VCCIO5	5		
GND	GNDIO5	-		
AD10	PB29A	5	BDQ33	T
AF10	PB29B	5	BDQ33	C
AC11	PB30A	5	BDQ33	T
AD11	PB30B	5	BDQ33	C
AG9	PB31A	5	BDQ33	T
AH9	PB31B	5	BDQ33	C
VCCIO	VCCIO5	99		
AE11	PB32A	5	BDQ33	T
AG10	PB32B	5	BDQ33	C
GND	GNDIO5	-		
AJ9	PB33A	5	BDQS33	T
AK9	PB33B	5	BDQ33	C
AF11	PB34A	5	BDQ33	T
AH10	PB34B	5	BDQ33	C
AC12	PB35A	5	BDQ33	T
AE12	PB35B	5	BDQ33	C
VCCIO	VCCIO5	5		
AD12	PB36A	5	BDQ33	T
AF12	PB36B	5	BDQ33	C
AJ10	PB37A	5	BDQ33	T
AK10	PB37B	5	BDQ33	C
GND	GNDIO5	-		
AG11	PB38A	5	BDQ42	T
AH11	PB38B	5	BDQ42	C
AE13	PB39A	5	BDQ42	T
AC13	PB39B	5	BDQ42	C
AF13	PB40A	5	BDQ42	T
VCCIO	VCCIO5	5		
AD13	PB40B	5	BDQ42	C
AJ11	PB41A	5	BDQ42	T
AK11	PB41B	5	BDQ42	C
AD14	PB42A	5	BDQS42	T
GND	GNDIO5	-		
AC14	PB42B	5	BDQ42	C
AG12	PB43A	5	BDQ42	T
AE14	PB43B	5	BDQ42	C
AJ12	PB44A	5	BDQ42	T
VCCIO	VCCIO5	5		
AK12	PB44B	5	BDQ42	C

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
P25	PR51B	2	RDQ54	C
VCCIO	VCCIO2	2		
P23	PR51A	2	RDQ54	T
P27	PR50B	2	RDQ54	C (LVDS)*
P28	PR50A	2	RDQ54	T (LVDS)*
GND	GNDIO2	-		
VCCIO	VCCIO2	2		
N24	PR39B	2	RUM0_SPLLC_FB_A/RDQ37	C
N26	PR39A	2	RUM0_SPLLT_FB_A/RDQ37	T
N23	PR38B	2	RUM0_SPLLC_IN_A/RDQ37	C
N25	PR38A	2	RUM0_SPLLT_IN_A/RDQ37	T
VCCIO	VCCIO2	2		
P29	PR37B	2	RDQ37	C (LVDS)*
P30	PR37A	2	RDQS37	T (LVDS)*
M26	PR36B	2	RDQ37	C
GND	GNDIO2	-		
M24	PR36A	2	RDQ37	T
N29	PR35B	2	RDQ37	C (LVDS)*
N30	PR35A	2	RDQ37	T (LVDS)*
M25	PR34B	2	RDQ37	C
VCCIO	VCCIO2	2		
M23	PR34A	2	RDQ37	T
M27	PR33B	2	RDQ37	C (LVDS)*
M28	PR33A	2	RDQ37	T (LVDS)*
L26	PR32B	2	RDQ29	C
GND	GNDIO2	-		
L24	PR32A	2	RDQ29	T
M29	PR31B	2	RDQ29	C (LVDS)*
M30	PR31A	2	RDQ29	T (LVDS)*
L25	PR30B	2	RDQ29	C
VCCIO	VCCIO2	2		
L23	PR30A	2	RDQ29	T
L27	PR29B	2	RDQ29	C (LVDS)*
L28	PR29A	2	RDQS29	T (LVDS)*
GND	GNDIO2	-		
K24	PR28B	2	RDQ29	C
K26	PR28A	2	RDQ29	T
L29	PR27B	2	RDQ29	C (LVDS)*
L30	PR27A	2	RDQ29	T (LVDS)*
VCCIO	VCCIO2	2		
K23	PR26B	2	RDQ29	C
K25	PR26A	2	RDQ29	T
K27	PR25B	2	RDQ29	C (LVDS)*

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
E21	PT76A	1		T
VCCIO	VCCIO1	1		
B22	PT75B	1		C
A22	PT75A	1		T
H20	PT74B	1		C
F21	PT74A	1		T
F20	PT73B	1		C
GND	GNDIO1	-		
H19	PT73A	1		T
D21	PT72B	1		C
C21	PT72A	1		T
E20	PT71B	1		C
VCCIO	VCCIO1	1		
G21	PT71A	1		T
B21	PT70B	1		C
A21	PT70A	1		T
F19	PT69B	1		C
G20	PT69A	1		T
E19	PT68B	1		C
GND	GNDIO1	-		
G19	PT68A	1		T
D20	PT67B	1		C
VCCIO	VCCIO1	1		
C20	PT67A	1		T
B20	PT66B	1		C
A20	PT66A	1		T
F18	PT65B	1		C
H18	PT65A	1		T
D19	PT64B	1		C
C19	PT64A	1		T
GND	GNDIO1	-		
G18	PT63B	1		C
E18	PT63A	1		T
H17	PT62B	1		C
F17	PT62A	1		T
VCCIO	VCCIO1	1		
G17	PT61B	1		C
E17	PT61A	1		T
B19	PT60B	1		C
A19	PT60A	1		T
GND	GNDIO1	-		
D17	PT59B	1		C
B18	PT59A	1		T

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C15	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B15	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C14	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A18	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C18	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B18	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C17	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B17	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
A16	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A17	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C16	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B14	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B13	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A14	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C13	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
-	-	-			GNDIO1	-		
-	-	-			VCCIO1	1		
E17	PT46B	1		C	PT55B	1		C
D17	PT46A	1		T	PT55A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
F17	PT45B	1		C	PT54B	1		C
D16	PT45A	1		T	PT54A	1		T
F19	PT44B	1		C	PT53B	1		C
F18	PT44A	1		T	PT53A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
E16	PT43B	1		C	PT52B	1		C
D15	PT43A	1		T	PT52A	1		T
G18	PT42B	1		C	PT51B	1		C
E15	PT42A	1		T	PT51A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
G17	PT41B	1		C	PT50B	1		C
E14	PT41A	1		T	PT50A	1		T
D14	PT40B	1		C	PT49B	1		C
D13	PT40A	1		T	PT49A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
F15	PT39B	1	VREF2_1	C	PT48B	1	VREF2_1	C
E12	PT39A	1	VREF1_1	T	PT48A	1	VREF1_1	T
H17	PT38B	1	PCLKC1_0	C	PT47B	1	PCLKC1_0	C
E13	PT38A	1	PCLKT1_0	T	PT47A	1	PCLKT1_0	T
C12	PT37B	0	PCLKC0_0	C	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
G15	PT37A	0	PCLKT0_0	T	PT46A	0	PCLKT0_0	T
C11	PT36B	0	VREF2_0	C	PT45B	0	VREF2_0	C
F14	PT36A	0	VREF1_0	T	PT45A	0	VREF1_0	T

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G7	PL8A	7	LDQ6	T (LVDS)*	NC	-		
G8	PL6A	7	LDQS6****	T (LVDS)*	NC	-		
G9	PL5A	7	LDQ6	T	NC	-		
H19	NC	-			NC	-		
H20	NC	-			NC	-		
H21	NC	-			NC	-		
H22	NC	-			NC	-		
H6	PL8B	7	LDQ6	C (LVDS)*	NC	-		
H8	PL5B	7	LDQ6	C	NC	-		
H9	PL2A	7	LDQ6	T (LVDS)*	NC	-		
J10	PL2B	7	LDQ6	C (LVDS)*	NC	-		
J20	NC	-			NC	-		
J21	NC	-			NC	-		
J9	PL4A	7	LDQ6	T (LVDS)*	NC	-		
K9	PL4B	7	LDQ6	C (LVDS)*	NC	-		
R9	NC	-			NC	-		
U22	NC	-			NC	-		
W9	NC	-			NC	-		
N13	VCCPLL	-			VCCPLL	-		
N18	VCCPLL	-			VCCPLL	-		
V13	VCCPLL	-			VCCPLL	-		
V18	VCCPLL	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
*** These sysCONFIG pins are dedicated I/O pins for configuration. The outpus are actively driven during normal device operation.
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U7	PL60A	6	VREF2_6/LDQ63	T
T8	PL60B	6	VREF1_6/LDQ63	C
R3	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6		
R2	PL61B	6	LDQ63	C (LVDS)*
R1	PL62A	6	LDQ63	T
T1	PL62B	6	LDQ63	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
T3	PL65A	6	LLM4_SPLLT_IN_A/LDQ63	T (LVDS)*
T2	PL65B	6	LLM4_SPLLC_IN_A/LDQ63	C (LVDS)*
U9	PL66A	6	LLM4_SPLLT_FB_A/LDQ63	T
U8	PL66B	6	LLM4_SPLLC_FB_A/LDQ63	C
GNDIO	GNDIO6	-		
U5	PL68A	6	LDQ72	T (LVDS)*
U4	PL68B	6	LDQ72	C (LVDS)*
V9	PL69A	6	LDQ72	T
V7	PL69B	6	LDQ72	C
VCCIO	VCCIO6	6		
U3	PL70A	6	LDQ72	T (LVDS)*
U2	PL70B	6	LDQ72	C (LVDS)*
V8	PL71A	6	LDQ72	T
U6	PL71B	6	LDQ72	C
GNDIO	GNDIO6	-		
U1	PL72A	6	LDQS72	T (LVDS)*
V2	PL72B	6	LDQ72	C (LVDS)*
V5	PL73A	6	LDQ72	T
VCCIO	VCCIO6	6		
V6	PL73B	6	LDQ72	C
V1	PL74A	6	LDQ72	T (LVDS)*
W1	PL74B	6	LDQ72	C (LVDS)*
W5	PL75A	6	LDQ72	T
GNDIO	GNDIO6	-		
W6	PL75B	6	LDQ72	C
W3	PL77A	6	LDQ81	T (LVDS)*
W4	PL77B	6	LDQ81	C (LVDS)*
W2	PL78A	6	LDQ81	T
Y4	PL78B	6	LDQ81	C
Y1	PL79A	6	LDQ81	T (LVDS)*
VCCIO	VCCIO6	6		
Y2	PL79B	6	LDQ81	C (LVDS)*
Y5	PL80A	6	LDQ81	T
Y6	PL80B	6	LDQ81	C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
GNDIO	GNDIO2	-		
M27	PR47B	2	RDQ45	C (LVDS)*
M28	PR47A	2	RDQ45	T (LVDS)*
H30	PR46B	2	RDQ45	C
G30	PR46A	2	RDQ45	T
VCCIO	VCCIO2	2		
M25	PR45B	2	RDQ45	C (LVDS)*
M26	PR45A	2	RDQS45	T (LVDS)*
L30	PR44B	2	RDQ45	C
GNDIO	GNDIO2	-		
L29	PR44A	2	RDQ45	T
L28	PR43B	2	RDQ45	C (LVDS)*
L27	PR43A	2	RDQ45	T (LVDS)*
H29	PR42B	2	RDQ45	C
VCCIO	VCCIO2	2		
G29	PR42A	2	RDQ45	T
L22	PR41B	2	RDQ45	C (LVDS)*
M22	PR41A	2	RDQ45	T (LVDS)*
F30	PR40B	2		C
GNDIO	GNDIO2	-		
F29	PR40A	2		T
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E30	PR34B	2	RDQ32	C (LVDS)*
E29	PR34A	2	RDQ32	T (LVDS)*
-	-	-		
L25	PR33B	2	RDQ32	C
L26	PR33A	2	RDQ32	T
VCCIO	VCCIO2	2		
H28	PR32B	2	RDQ32	C (LVDS)*
J28	PR32A	2	RDQS32	T (LVDS)*
G28	PR31B	2	RDQ32	C
GNDIO	GNDIO2	-		
G27	PR31A	2	RDQ32	T
L24	PR30B	2	RDQ32	C (LVDS)*
L23	PR30A	2	RDQ32	T (LVDS)*
D30	PR29B	2	RDQ32	C
VCCIO	VCCIO2	2		
D29	PR29A	2	RDQ32	T
K24	PR28B	2	RDQ32	C (LVDS)*
K25	PR28A	2	RDQ32	T (LVDS)*
J27	PR26B	2	RDQ23	C
GNDIO	GNDIO2	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AE12	NC	-			NC	-		
AE13	NC	-			NC	-		
AE19	NC	-			NC	-		
AE21	NC	-			NC	-		
AE22	NC	-			NC	-		
AE23	NC	-			NC	-		
AF11	NC	-			NC	-		
AF21	NC	-			NC	-		
AF22	NC	-			NC	-		
AF24	NC	-			NC	-		
AF8	NC	-			NC	-		
AF9	NC	-			NC	-		
AG10	NC	-			NC	-		
AG11	NC	-			NC	-		
AG24	NC	-			NC	-		
AG25	NC	-			NC	-		
AG26	NC	-			NC	-		
AG3	NC	-			NC	-		
AG7	NC	-			NC	-		
AG8	NC	-			NC	-		
AG9	NC	-			NC	-		
AH10	NC	-			NC	-		
AH11	NC	-			NC	-		
AH13	NC	-			NC	-		
AH24	NC	-			NC	-		
AH25	NC	-			NC	-		
AH26	NC	-			NC	-		
AH27	NC	-			NC	-		
AH5	NC	-			NC	-		
AH6	NC	-			NC	-		
AH7	NC	-			NC	-		
AH8	NC	-			NC	-		
AH9	NC	-			NC	-		
AJ10	NC	-			NC	-		
AJ11	NC	-			NC	-		
AJ13	NC	-			NC	-		
AJ24	NC	-			NC	-		
AJ25	NC	-			NC	-		
AJ26	NC	-			NC	-		
AJ27	NC	-			NC	-		
AJ3	NC	-			NC	-		
AJ4	NC	-			NC	-		
AJ5	NC	-			NC	-		
AJ6	NC	-			NC	-		
AJ7	NC	-			NC	-		
AJ8	NC	-			NC	-		
AJ9	NC	-			NC	-		
AK10	NC	-			NC	-		
AK11	NC	-			NC	-		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	COM	35
LFE2-35E-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	COM	35
LFE2-35E-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	COM	35
LFE2-35E-5FN672C	450	1.2V	-5	Lead-Free fpBGA	672	COM	35
LFE2-35E-6FN672C	450	1.2V	-6	Lead-Free fpBGA	672	COM	35
LFE2-35E-7FN672C	450	1.2V	-7	Lead-Free fpBGA	672	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5FN484C	339	1.2V	-5	Lead-Free fpBGA	484	COM	50
LFE2-50E-6FN484C	339	1.2V	-6	Lead-Free fpBGA	484	COM	50
LFE2-50E-7FN484C	339	1.2V	-7	Lead-Free fpBGA	484	COM	50
LFE2-50E-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	COM	50
LFE2-50E-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	COM	50
LFE2-50E-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	COM	70
LFE2-70E-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	COM	70
LFE2-70E-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	COM	70
LFE2-70E-5FN900C	583	1.2V	-5	Lead-Free fpBGA	900	COM	70
LFE2-70E-6FN900C	583	1.2V	-6	Lead-Free fpBGA	900	COM	70
LFE2-70E-7FN900C	583	1.2V	-7	Lead-Free fpBGA	900	COM	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5TN144I	90	1.2V	-5	Lead-Free TQFP	144	IND	6
LFE2-6E-6TN144I	90	1.2V	-6	Lead-Free TQFP	144	IND	6
LFE2-6E-5FN256I	190	1.2V	-5	Lead-Free fpBGA	256	IND	6
LFE2-6E-6FN256I	190	1.2V	-6	Lead-Free fpBGA	256	IND	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5TN144I	93	1.2V	-5	Lead-Free TQFP	144	IND	12
LFE2-12E-6TN144I	93	1.2V	-6	Lead-Free TQFP	144	IND	12
LFE2-12E-5QN208I	131	1.2V	-5	Lead-Free PQFP	208	IND	12
LFE2-12E-6QN208I	131	1.2V	-6	Lead-Free PQFP	208	IND	12
LFE2-12E-5FN256I	193	1.2V	-5	Lead-Free fpBGA	256	IND	12
LFE2-12E-6FN256I	193	1.2V	-6	Lead-Free fpBGA	256	IND	12
LFE2-12E-5FN484I	297	1.2V	-5	Lead-Free fpBGA	484	IND	12
LFE2-12E-6FN484I	297	1.2V	-6	Lead-Free fpBGA	484	IND	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35SE-5F484C	331	1.2V	-5	fpBGA	484	Com	35
LFE2-35SE-6F484C	331	1.2V	-6	fpBGA	484	Com	35
LFE2-35SE-7F484C	331	1.2V	-7	fpBGA	484	Com	35
LFE2-35SE-5F672C	450	1.2V	-5	fpBGA	672	Com	35
LFE2-35SE-6F672C	450	1.2V	-6	fpBGA	672	Com	35
LFE2-35SE-7F672C	450	1.2V	-7	fpBGA	672	Com	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50SE-5F484C	339	1.2V	-5	fpBGA	484	Com	50
LFE2-50SE-6F484C	339	1.2V	-6	fpBGA	484	Com	50
LFE2-50SE-7F484C	339	1.2V	-7	fpBGA	484	Com	50
LFE2-50SE-5F672C	500	1.2V	-5	fpBGA	672	Com	50
LFE2-50SE-6F672C	500	1.2V	-6	fpBGA	672	Com	50
LFE2-50SE-7F672C	500	1.2V	-7	fpBGA	672	Com	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70SE-5F672C	500	1.2V	-5	fpBGA	672	Com	70
LFE2-70SE-6F672C	500	1.2V	-6	fpBGA	672	Com	70
LFE2-70SE-7F672C	500	1.2V	-7	fpBGA	672	Com	70
LFE2-70SE-5F900C	583	1.2V	-5	fpBGA	900	Com	70
LFE2-70SE-6F900C	583	1.2V	-6	fpBGA	900	Com	70
LFE2-70SE-7F900C	583	1.2V	-7	fpBGA	900	Com	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6SE-5T144I	90	1.2V	-5	TQFP	144	Ind	6
LFE2-6SE-6T144I	90	1.2V	-6	TQFP	144	Ind	6
LFE2-6SE-5F256I	190	1.2V	-5	fpBGA	256	Ind	6
LFE2-6SE-6F256I	190	1.2V	-6	fpBGA	256	Ind	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12SE-5T144I	93	1.2V	-5	TQFP	144	Ind	12
LFE2-12SE-6T144I	93	1.2V	-6	TQFP	144	Ind	12
LFE2-12SE-5Q208I	131	1.2V	-5	PQFP	208	Ind	12
LFE2-12SE-6Q208I	131	1.2V	-6	PQFP	208	Ind	12
LFE2-12SE-5F256I	193	1.2V	-5	fpBGA	256	Ind	12
LFE2-12SE-6F256I	193	1.2V	-6	fpBGA	256	Ind	12
LFE2-12SE-5F484I	297	1.2V	-5	fpBGA	484	Ind	12
LFE2-12SE-6F484I	297	1.2V	-6	fpBGA	484	Ind	12

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20SE-5F484I	304	1.2V	-5	fpBGA	484	Ind	20
LFE2M20SE-6F484I	304	1.2V	-6	fpBGA	484	Ind	20
LFE2M20SE-5F256I	140	1.2V	-5	fpBGA	256	Ind	20
LFE2M20SE-6F256I	140	1.2V	-6	fpBGA	256	Ind	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35SE-5F672I	410	1.2V	-5	fpBGA	672	Ind	35
LFE2M35SE-6F672I	410	1.2V	-6	fpBGA	672	Ind	35
LFE2M35SE-5F484I	303	1.2V	-5	fpBGA	484	Ind	35
LFE2M35SE-6F484I	303	1.2V	-6	fpBGA	484	Ind	35
LFE2M35SE-5F256I	140	1.2V	-5	fpBGA	256	Ind	35
LFE2M35SE-6F256I	140	1.2V	-6	fpBGA	256	Ind	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50SE-5F900I	410	1.2V	-5	fpBGA	900	Ind	50
LFE2M50SE-6F900I	410	1.2V	-6	fpBGA	900	Ind	50
LFE2M50SE-5F672I	372	1.2V	-5	fpBGA	672	Ind	50
LFE2M50SE-6F672I	372	1.2V	-6	fpBGA	672	Ind	50
LFE2M50SE-5F484I	270	1.2V	-5	fpBGA	484	Ind	50
LFE2M50SE-6F484I	270	1.2V	-6	fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5F1152I	436	1.2V	-5	fpBGA	1152	Ind	70
LFE2M70SE-6F1152I	436	1.2V	-6	fpBGA	1152	Ind	70
LFE2M70SE-5F900I	416	1.2V	-5	fpBGA	900	Ind	70
LFE2M70SE-6F900I	416	1.2V	-6	fpBGA	900	Ind	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5F1152I	520	1.2V	-5	fpBGA	1152	Ind	100
LFE2M100SE-6F1152I	520	1.2V	-6	fpBGA	1152	Ind	100
LFE2M100SE-5F900I	416	1.2V	-5	fpBGA	900	Ind	100
LFE2M100SE-6F900I	416	1.2V	-6	fpBGA	900	Ind	100

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.